



ATTY DOCKET #: IIZ.003D2C



APPLICANT: Takashi Ohsumi **DUE DATE:**

SERIAL NO.: 10/689,936

FILING DATE: October 22, 2003

TITLE: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL
STRESS

RECEIPT OF THE FOLLOWING PAPERS IS ACKNOWLEDGED:

Transmittal of Information Disclosure Statement; Statement Under 37 C.F.R.
1.97(e) Accompanying Information Disclosure Statement; PTO/SB/08A Form;
and Letter of Related Application.

DATE: April 25, 2005

ATTY: AJT

[Check No. N/A]

BEST AVAILABLE COPY

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
HIZ.003D2C

In Re Application Of: Takashi Ohsumi

Application No.

10/689,936

Filing Date

October 22, 2003

Examiner

F. Toledo

Customer No.

Group Art Unit

2823

Confirmation No.

4027

Title: **A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS**

Address to:

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

37 CFR 1.97(b)

1. ☐ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

2. ☒ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

☒ the statement specified in 37 CFR 1.97(e);

OR

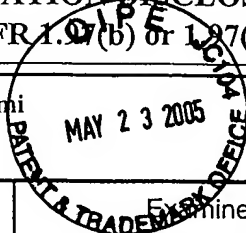
☐ the fee set forth in 37 CFR 1.17(p).

Note: The references listed on Form PTO/SB/08A were cited in copending U.S. Application Serial No. 10/957,620, and thus may be material to the prosecution of the present application.

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
IIZ.003D2C

In Re Application: Takashi Ohsumi



Application No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo	Customer No.	Group Art Unit 2823	Confirmation No. 4027
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Title: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of _____ is attached.
- ☒ The Director is hereby authorized to charge and credit Deposit Account No. 50-0238 as described below.
- ☐ Charge the amount of _____
- ☒ Credit any overpayment.
- ☒ Charge any additional fee required.
- ☐ Payment by credit card. Form PTO-2038 is attached.

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

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*This certificate may only be used if paying by deposit account.

Signature

Dated: April 25, 2005

ANDREW J. TELESZ, JR.
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CC:

STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT

Docket No.
IIZ.003D2C

In Re Application Of: Takashi Ohsumi

MAY 23 2005

Application No.
10/689,936

Filing Date
October 22, 2003

Examiner
F. Toledo

Customer No.

Group Art Unit
2823

Confirmation No.
4027

Invention: A METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING
MEMBER WITH REDUCED THERMAL STRESS

COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- ☐ Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- ☒ No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.


Signature

ANDREW J. TELESZ, JR.
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Dated: April 25, 2005

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